Release notes for ISSDK v1.8 Rev. 4.0 — 15 August 2024

Release notes

Document information

| Information | Content |
|-------------|---|
| Keywords | IoT Sensing SDK, ISSDK, MCUXpresso, middleware |
| Abstract | Release notes for IoT Sensing SDK (ISSDK) v1.8 middleware |



1 Overview

The IoT Sensing Software Development Kit (ISSDK) is the embedded software framework enabling NXP's digital and analog sensors platforms for industrial and medical IoT applications. ISSDK provides a unified set of sensor support models that target NXP's portfolio of sensors across a broad range of ARM Cortex corebased Microcontrollers. ISSDK is offered as a middleware component in MCUXpresso SDK for supported microcontrollers. ISSDK relies on the MCUXpreso SDK 2.x drivers and project release infrastructure to create a unified user experience. ISSDK v1.8 combines a set of robust sensor drivers and algorithms along with example applications to allow a user to get started using NXP sensors quickly.

2 Features

- Enables rapid prototyping and production applications using NXP sensors.
- Provides NXP's sensor register definitions, register access interfaces and sensor level multiple register read/ write interfaces.
- Enables easy porting across broad range of NXP's Arm Cortex M based Microcontrollers by using Arm CMSIS Driver APIs.
- Leverages MCUXpresso SDK (Kinetis, LPC, MCX, and i.MX SDK) drivers and release infrastructure.
- Provides out-of-box examples and reference software demonstrating configuration and usage of sensors in various supported modes along with application examples using NXP's sensors.
- Provides bare metal and FreeRTOS based reference examples using NXP's sensors.
- Provides reference algorithm examples, libraries and interfaces to access algorithms like sensor fusion and pedometer.
- Provides out-of-box sensor demonstration projects using FreeMASTER Sensor Tool.
- Supports multiple toolchains: MCUXpresso, IAR, KEIL MDK, Arm GCC.

2.1 Supported sensors

The following NXP sensors are supported by ISSDK v1.8:

| Sensor part number | Sensor type | Interface | | |
|-----------------------------|---|-----------|------------------|-----|
| | | SPI | I ² C | ADC |
| FXAS21002C ^[1] | Gyroscope | 1 | ~ | - |
| FXLC95000CL ^[1] | Intelligent accelerometer | ~ | ~ | |
| FXLS8471QR1 ^[1] | Digital accelerometer | ~ | ~ | |
| FXLS8961AF | 3-axis accelerometer with high performance over temperature | 1 | ~ | |
| FXLS8962AFR1 ^[1] | Low power, 12-bit, 3-axis digital accelerometer | 1 | 1 | _ |
| FXLS8964AFR3 | Low power, 12-bit, 3-axis accelerometer for automotive keyfob applications. | ~ | 1 | _ |
| FXLS8967AFR3 | Low power, 12-bit, 3-axis digital accelerometer for automotive comfort and safety applications. | ~ | ~ | - |
| FXLS8971CF | 3-axis accelerometer with high performance over temperature | ~ | ~ | |
| FXLS8974CFR3 | Low power, 12-bit, 3-axis digital accelerometer for industrial/mechanical IoT applications. | 1 | 1 | - |

Table 1. Sensors supported by ISSDK v1.8

Release notes for ISSDK v1.8

| Sensor part number | Sensor type | Interface | | |
|----------------------------|---|-----------|------------------|-----|
| | | SPI | I ² C | ADC |
| FXOS8700CQ ^[1] | Digital accelerometer and magnetometer | 1 | 1 | _ |
| FXPQ3115BV | Pressure/Bio-Compatible | _ | 1 | _ |
| FXPS7250A4 | Analog absolute pressure sensor, 20 kPa to 250 kPa | — | — | ✓ |
| FXPS7250D4 | High-performance, high-precision, barometric absolute pressure sensor | _ | ~ | — |
| MAG3110 ^[1] | Digital magnetometer | | ~ | _ |
| MMA845xQR1 ^[1] | Digital accelerometer | _ | ~ | _ |
| MMA8491Q ^[1] | Digital accelerometer | _ | 1 | _ |
| MMA8652FCR1 ^[1] | Digital accelerometer | _ | ~ | _ |
| MMA9553 ^[1] | Intelligent accelerometer | _ | 1 | _ |
| MPL3115A2 | Digital pressure | _ | ~ | |
| MPXV5004DP | Differential and gauge, integrated analog pressure sensor | _ | - | ~ |
| NMH1000 | Magnetic Switch Sensor | | ~ | |

Table 1. Sensors supported by ISSDK v1.8...continued

[1] Sensor part EOL

2.2 Supported algorithms

ISSDK v1.8 supports Sensor Fusion V7.2.x algorithm deployed as example applications and source code libraries.

ISSDK v1.8 supports a pedometer algorithm V1.0 deployed as example applications, interface files and a binary library.

3 Development tools

The ISSDK v1.8 is supported with the following development toolchains:

- MCUXpresso IDE v11.10.0
- IAR Embedded Workbench for ARM version v9.60.1
- MDK-ARM Microcontroller Development Kit (Keil) v5.38.0
- Makefiles support with GCC revision 13.2.1 from ARM Embedded

4 PC configurations

The system configurations required to use ISSDK v1.8 supported development toolchains are as follows:

Table 2. PC configurations

| Parameter | Minimum configuration | Recommended configuration |
|-----------------------------------|-----------------------|---------------------------|
| Operating system | Windo | ows 10 |
| Communications to target hardware | USB | port |
| Processor speed in GHz | 1.8 | 2.6 |
| RAM in GB | 4 | 8 |
| Free disk space in GB | 20 | 400 |

5 Supported development systems

ISSDK v1.8 is designed to be distributed as codebases created by MCUXpresso SDK Builder targeting a particular sensor demonstration kit. A sensor demonstration kit is defined as a known combination of a Freedom Development Board and an Arduino compatible Sensor Shield board. MCUXpresso SDK Builder allows selection of these kits as input configurations to the SDK Builder.

The following standard (Table 3) and custom (Table 4) sensor kits are supported by ISSDK v1.8:

- Standard sensor kits are official MCU board sensor shield kits which are available for end user to order from NXP Sensor Evaluation Boards web page.
- Custom sensor kits are board shield pairs which will not be available for end user to order as official MCU board sensor shield kits (MCU board and sensor shield must be ordered separately).

 Table 3. Standard sensor kits supported by ISSDK v1.8

| | - | |
|------------------|-----------|---------------------------------|
| Sensor kit | MCU board | Sensor shield board |
| FRDM-K22F-A8964 | FRDM-K22F | FRDM-STBA-A8964 |
| FRDM-K22F-A8974 | FRDM-K22F | FRDM-STBI-A8974 |
| FRDM-K22F-AGMP03 | FRDM-K22F | FRDM-STBC-AGMP03 ^[1] |

Release notes for ISSDK v1.8

| Table 3. Standard sensor kits supported by ISSDK v1.8continued | | | |
|--|---|--|--|
| MCU board | Sensor shield board | | |
| FRDM-K22F | FRDM-STBC-AGM01 ^[1] | | |
| FRDM-K22F | FRDM-STBC-SA9500 ^[1] | | |
| FRDM-K64F | FRDM-STBC-AGM01 ^[1] | | |
| FRDM-K64F | FRDM-STBC-AGM04 ^[1] | | |
| FRDM-KE15Z | FRDMSTBCDP5004 | | |
| FRDM-KL25Z | Using on-board MMA8451 | | |
| FRDM-KE15Z | FRDMSTBI-NMH1000 | | |
| FRDM-KL25Z | FRDMSTBC-A8471 ^[1] | | |
| FRDM-KL25Z | FRDMSTBC-A8491 ^[1] | | |
| FRDM-KL25Z | FRDMSTBC-P3115 | | |
| FRDM-KL27Z | Using on-board MMA8451, MAG3110 | | |
| FRDM-KL27Z | FRDMSTBI-B3115 | | |
| LPC55S16-EVK | FRDM-STBA-A8961 | | |
| LPC55S16-EVK | FRDM-STBI-A8971 | | |
| | MCU boardFRDM-K22FFRDM-K22FFRDM-K64FFRDM-K64FFRDM-KE15ZFRDM-KL25ZFRDM-KL25ZFRDM-KL25ZFRDM-KL25ZFRDM-KL25ZFRDM-KL25ZFRDM-KL25ZFRDM-KL25ZFRDM-KL25ZFRDM-KL25ZFRDM-KL25ZFRDM-KL25ZFRDM-KL25ZFRDM-KL25ZFRDM-KL25ZFRDM-KL25ZFRDM-KL25ZFRDM-KL25ZFRDM-KL27ZLPC55S16-EVK | | |

Table 3. Standard sensor kits supported by ISSDK v1.8...continued

[1] Sensor shield board is EOL

| EVKB-IMXRT1050 with AGM01 | EVKB-IMXRT1050 | FRDM-STBC-AGM01 ^[1] |
|---------------------------|-----------------|---------------------------------|
| EVK-MIMXRT1010 with AGM01 | EVK-MIMXRT1010 | FRDM-STBC-AGM01 ^[1] |
| EVK-MIMXRT1015 with AGM01 | EVK-MIMXRT1015 | FRDM-STBC-AGM01 ^[1] |
| EVK-MIMXRT1020 with AGM01 | EVK-MIMXRT1020 | FRDM-STBC-AGM01 ^[1] |
| EVK-MIMXRT1040 with A8974 | EVK-MIMXRT1040 | FRDM-STBI-A8974 |
| EVK-MIMXRT1050 with AGM01 | EVK-MIMXRT1050 | FRDM-STBC-AGM01 ^[1] |
| EVK-MIMXRT1060 with AGM01 | EVK-MIMXRT1060 | FRDM-STBC-AGM01 ^[1] |
| EVK-MIMXRT1064 with AGM01 | EVK-MIMXRT1064 | FRDM-STBC-AGM01 ^[1] |
| EVK-MIMXRT1170 with AGM01 | EVK- MIMXRT1170 | FRDM-STBC-AGM01 ^[1] |
| EVK-MIMXRT595 with AGM01 | EVK-IMXRT595 | FRDM-STBC-AGM01 ^[1] |
| FRDM-K22F with A8961 | FRDM-K22F | FRDM-STBA-A8961 |
| FRDM-K22F with A8967 | FRDM-K22F | FRDM-STBA-A8967 |
| FRDM-K22F with A8971 | FRDM-K22F | FRDM-STBI-A8971 |
| FRDM-K32L3A6 with AGM01 | FRDM-K32L3A6 | FRDM-STBC-AGM01 ^[1] |
| FRDM-K32W042 with AGM01 | FRDM-K32W042 | FRDM-STBC-AGM01 ^[1] |
| FRDM-K64F with MULT2B | FRDM-K64F | FRDM-FXS-MULT2-B ^[1] |
| FRDMKE15-NMH1000 | FRDM-KE15Z | FRDMSTBI-NMH1000 |
| FRDM-KE15Z with PA7250 | FRDM-KE15Z | FRDM-STBA-PA7250 |
| FRDM-KE15Z with PD7250 | FRDM-KE15Z | FRDM-STBA-PD7250 |
| L | I | |

| Table 4. Custom sensor kits supporte | d by ISSDK v1.8continued | |
|--|--------------------------|--|
| FRDM-KL27Z with A8471 | FRDM-KL27Z | FRDM-STBC-A8471 ^[1] |
| FRDM-KL27Z with A8491 | FRDM-KL27Z | FRDM-STBC-A8491 ^[1] |
| FRDM-KL27Z with P3115 | FRDM-KL27Z | FRDM-STBC-P3115 |
| FRDM-MCXA153 with A8974 | FRDM-MCXA153 | FRDM-STBI-A8974 |
| FRDM-MCXA156 with A8974 | FRDM-MCXA156 | FRDM-STBI-A8974 |
| FRDM-MCXN947 with A8974 | FRDM-MCXN947 | FRDM-STBI-A8974 |
| FRDM-MCXW71 with A8974 | FRDM-MCXW71 | FRDM-STBI-A8974 |
| K32W148-EVK with A8974 | K32W148-EVK | FRDM-STBI-A8974 |
| KW45B41Z-EVK with A8974 | KW45B41Z-EVK | FRDM-STBI-A8974 |
| LPCXpresso54114 with AGM01 | LPXCpresso54114 | FRDM-STBC-AGM01 ^[1] |
| LPCXpresso55S06 with AGM01 | LPCXpresso55S06-EVK | FRDM-STBC-AGM01 ^[1] |
| LPCXpresso55S16 with FRDM-STBA- A8964 | LPCXpresso55S16 | FRDM-STBA-A8964 |
| LPCXpresso55S16 with FRDM-STBA- A8967 | LPCXpresso55S16 | FRDM-STBA-A8967 |
| LPCXpresso55S16 with FRDM-STBC- AGM01 | LPCXpresso55S16 | FRDM-STBC-AGM01 ^[1] |
| LPCXpresso55S16 with FRDM-STBI- A8974 | LPCXpresso55S16 | FRDM-STBI-A8974 |
| LPCXpresso55s69 with AGM01 | LPCXpresso55s69 | FRDM-STBC-AGM01 ^[1] |
| MCXN-5xx-EVK with A8974 | MCXN-9xx-EVK | FRDM-STBI-A8974 |
| MCXN-9xx-EVK with A8974 | MCXN-9xx-EVK | FRDM-STBI-A8974 |
| MEK-MIMX8QM | MEK-MIMX8QM | Using on-board FXOS8700, FXAS21002, MPL3115, ISL29023 |
| MIMXRT1024-EVK with AGM01 | MIMXRT1024-EVK | FRDM-STBC-AGM01 ^[1] |
| MIMXRT1060-EVK with A8974 | MIMXRT1060-EVK | FRDM-STBI-A8974 |
| MIMXRT1180-EVK with A8974 | MIMXRT1180-EVK | FRDM-STBI-A8974 |
| MIMXRT685-EVK with FRDM-STBC- AGM01 | MIMXRT685-EVK | FRDM-STBC-AGM01 ^[1] |
| MIMXRT700-EVK with A8974 | MIMXRT700-EVK | FRDM-STBI-A8974 |
| L | 1 | 1 |

Table 4. Custom sensor kits supported by ISSDK v1.8...continued

[1] Sensor shield board is EOL

6 Release contents

| Table 5. Release contents | | |
|---------------------------|---|---|
| Deliverable | Location | Details |
| Kits | <install_dir>/boards/<kit_name></kit_name></install_dir> | Sensor board kit files and examples. |
| Sensor driver examples | <install_dir>/boards/<kit_name>/issdk_examples/sensors</kit_name></install_dir> | ISSDK reference sensor driver examples for chosen sensor kit. |

| Deliverable | Location | Details |
|-------------------------------------|--|---|
| Algorithm examples | <install_dir>/boards/<kit_name>/issdk_examples/algorithms</kit_name></install_dir> | ISSDK reference algorithm examples for chosen kit. |
| Board kit specific configuration | <install_dir>/middleware/issdk/boardkit</install_dir> | ISSDK source files containing board-shield mapping files for sensor kits. |
| CMSIS driver Implementations | <install_dir>/middleware/issdk/drivers</install_dir> | ISSDK source files for ISSDK specific additional drivers. |
| Documentation | <install_dir>/docs/ISSDK</install_dir> | ISSDK documentation |
| Middleware | <install_dir>/middleware/issdk</install_dir> | ISSDK middleware sources deployed in MCUXpresso SDK package |
| Sensor algorithms | <install_dir>/middleware/issdk/algorithms</install_dir> | ISSDK algorithm sources |
| Driver examples | <install_dir>/middleware/issdk/driverexamples</install_dir> | ISSDK sensor driver example sources |
| Sensor drivers | <install_dir>/middleware/issdk/sensors</install_dir> | ISSDK sensor driver sources with sensor register definition files |
| CMSIS Driver API Includes | <install_dir>/CMSIS/Driver/Include</install_dir> | ISSDK CMSIS driver includes |

Table 5. Release contents...continued

7 MISRA compliance

All MCUXpresso SDK drivers comply to MISRA 2012 rules with exceptions in

| Exception rules | Description |
|-----------------|---|
| Directive 4.4 | Sections of code should not be commented out. |
| Directive 4.5 | Identifiers in the same name space with overlapping visibility should be typographically unambiguous. |
| Directive 4.6 | Typedefs that indicate size and signedness should be used in place of the basic numerical types. |
| Directive 4.8 | If a pointer to a structure or union is never dereferenced within a translation unit, then the implementation of the object should be hidden. |
| Directive 4.9 | A function should be used in preference to a function-like macro where they are interchangeable. |
| Directive 4.13 | Functions which are designed to provide operations on a resource should be called in an appropriate sequence. |
| Rule 1.2 | Language extensions should not be used. |
| Rule 2.3 | A project should not contain unused type declarations. |
| Rule 2.4 | A project should not contain unused tag declarations. |
| Rule 2.5 | A project should not contain unused macro declarations. |
| Rule 2.6 | A function should not contain unused label declarations. |
| Rule 2.7 | There should be no unused parameters in functions. |
| Rule 4.2 | Trigraphs should not be used. |
| Rule 5.1 | External identifiers shall be distinct. |

Table 6. MISRA exception rules

| Exception rules | Description |
|-----------------|---|
| Rule 5.4 | Macro identifiers shall be distinct. |
| Rule 5.9 | Identifiers that define objects or functions with internal linkage should be unique. |
| Rule 8.7 | Functions and objects should not be defined with external linkage if they are referenced in only one translation unit. |
| Rule 8.9 | An object should be defined at block scope if its identifier only appears in a single function. |
| Rule 8.11 | When an array with external linkage is declared, its size should be explicitly specified. |
| Rule 8.13 | A pointer should point to a const-qualified type whenever possible. |
| Rule 10.5 | The value of an expression should not be cast to an inappropriate essential type. |
| Rule 11.4 | A conversion should not be performed between a pointer to object and an integer type. |
| Rule 11.5 | A conversion should not be performed from pointer to void into pointer to object. |
| Rule 12.1 | The precedence of operators within expressions should be made explicit. |
| Rule 12.3 | The comma operator should not be used. |
| Rule 12.4 | Evaluation of constant expressions should not lead to unsigned integer wrap-around. |
| Rule 13.3 | A full expression containing an increment (++) or decrement (-) operator should have no other potential side effects other than that caused by the increment or decrement operator. |
| Rule 15.4 | There should be no more than one break or go to statement used to terminate any iteration statement. |
| Rule 17.5 | The function argument corresponding to a parameter declared to have an array type shall have an appropriate number of elements. |
| Rule 18.8 | A function parameter should not be modified. |
| Rule 19.2 | The union keyword should not be used. |
| Rule 20.1 | #include directives should only be preceded by preprocessor directives or comments. |
| Rule 20.10 | The # and ## preprocessor operators should not be used. |
| Rule 21.1 | #define and #undef shall not be used on a reserved identifier or reserved macro name. |
| Rule 21.2 | A reserved identifier or macro name shall not be declared. |
| Rule 21.12 | The exception handling features of <fenv.h> should not be used.</fenv.h> |
| | |

Table 6. MISRA exception rules...continued

8 Open and closed defects

8.1 ISSDK v1.8 open defects

There are no open defects in ISSDK v1.8.

8.2 ISSDK v1.8 closed defects

There are no closed defects in ISSDK v1.8 (no open defects reported in ISSDK v1.7).

9 Known issues

There are no known issues in this software release. For known issues in MCUXpresso SDK 2.12.0, refer to the release notes for MCUXpresso SDK.

10 Change log

10.1 What is new in ISSDK v1.8

- ISSDK middleware component integrated with MCUXpresso SDK 2.16.0 ecosystem.
- ISSDK enablement for FXLS8964AF 3 axis accelerometer for automotive keyfob applications.
 - Added FXLS8964AF sensor driver
 - Added FRDM-K22F-A8964 (sensor evaluation kit for FXLS8964AF) and reference examples into MCUXpresso SDK.
- ISSDK enablement for FXLS8967AF 3 axis accelerometer for automotive security and convenience applications.
 - Added FXLS8967AF sensor driver
 - Added custom kit FRDM-K22F with A8967 (sensor evaluation kit for FXLS8967AF) and reference examples into MCUXpresso SDK.
- ISSDK enablement for FXLS8974CF 3 axis accelerometer for industrial/medical IoT applications.
 - Added FXLS8974CF sensor driver
 - Added sensor kit FRDM-K22F-A8974 (sensor evaluation kit for FXLS8974CF) and reference examples into MCUXpresso SDK.
- ISSDK FXLS8964AF, FXLS8967AF, FXLS8974CF sensors enablement on LPCXpresso55S16
 - Added FXLS8964AF sensor examples for LPCXpresso55S16 custom kit with FRDMSTBA-A8964 shield board in MCUXpresso.
 - Added FXLS8967AF sensor examples for LPCXpresso55S16 custom kit with FRDMSTBA-A8967 shield board in MCUXpresso.
 - Added FXLS8974CF sensor examples for LPCXpresso55S16 custom kit with FRDMSTBI-A8974 shield board in MCUXpresso
- ISSDK enablement for FXLS8961AF 3 axis accelerometer for automotive applications requiring high performance over temperature
 - Added FXLS8961AF sensor driver
 - Added custom kit with LPC55S16-EVK and FRDM-STBA-A8964 (sensor evaluation kit for FXLS8961AF) and reference examples into MCUXpresso SDK.
- ISSDK enablement for FXLS8971CF 3 axis accelerometer for industrial/medical IoT applications requiring high performance over temperature.
 - Added FXLS8971CF sensor driver
 - Added kit LPC55S16-EVK-A8971CF (sensor evaluation kit for FXLS8971CF) and reference examples into MCUXpresso SDK.
- ISSDK enablement for NMH1000 ultra-low power magnetic switch sensor.
- Added NMH1000 sensor driver
- Added custom kit FRDM-KE15Z with FRDMSTBI-NMH1000 (sensor evaluation kit for NMH1000) and reference examples into MCUXpresso SDK.
- ISSDK FXLS8974CF sensors enablement on FRDM-MCXN947, FRDM-MCXA153, FRDM-MCXA156, K32W148-EVK, KW45B41Z-EVK, MIMXRT700-EVK, MIMXRT1180-EVK, MIMXRT1060-EVK and FRDM-MCXW71.

10.2 What is new in ISSDK v1.7

- ISSDK middleware component integrated with MCUXpresso SDK 2.10.0 Rel 14 ecosystem
- Added ISSDK examples for FreeMASTER Sensor Tool using FreeMASTER communication drivers.
 - Added FXLS8962 ISSDK example project for FreeMASTER Sensor Tool.

Added FXOS8700 ISSDK example project for FreeMASTER Sensor Tool.

Added MMA8652 ISSDK example project for FreeMASTER Sensor Tool.

ISSDK enablement on LPCXpresso55S06

Added sensors examples for LPCXpresso55S06 custom kit with FRDM-STBC-AGM01 in MCUXpresso
 ISSDK enablement on EVK-MIMXRT1170

- Added sensors examples for EVK-MIMXRT1170 custom kit with FRDM-STBC-AGM01 in MCUXpresso
 ISSDK enablement on MIMXRT1024-EVK
- Added sensors examples for MIMXRT1024-EVK custom kit with FRDM-STBC-AGM01 in MCUXpresso
- ISSDK enablement on EVK-MIMXRT595
- Added sensors examples for EVK-MIMXRT595 custom kit with FRDM-STBC-AGM01 in MCUXpresso
 ISSDK enablement on LPC55S16-EVK
- Added sensors examples for LPCXpresso55S16 custom kit with FRDM-STBC-AGM01 in MCUXpresso
 ISSDK enablement on MIMXRT685-EVK
 - Added sensors examples for MIMXRT685-EVK custom kit with FRDM-STBC-AGM01 in MCUXpresso
- ISSDK enablement on EVKB-IMXRT1050

Added sensors examples for EVKB-IMXRT1050 custom kit with FRDM-STBC-AGM01 in MCUXpresso
 ISSDK enablement for EVK-MIMXRT1010

- Added sensor examples for EVK-MIMXRT1010 custom kit with FRDM-STBC-AGM01 in MCUXpresso
- ISSDK enablement on EVK-MIMXRT1015
 Added sensors examples for EVK-MIMXRT1015 custom kit with FRDM-STBC-AGM01 in MCUXpresso
 ISSDK enablement on EVK-MIMXRT1020
- Added sensors examples for EVK-MIMXRT1020 custom kit with FRDM-STBC-AGM01 in MCUXpresso
 ISSDK enablement on EVK-MIMXRT1060
- Added sensors examples for EVK-MIMXRT1060 custom kit with FRDM-STBC-AGM01 in MCUXpresso
 ISSDK enablement on EVK-MIMXRT1064
- Added sensors examples for EVK-MIMXRT1064 custom kit with FRDM-STBC-AGM01 in MCUXpresso
- ISSDK enablement for FRDM-K32L3A6
 Added sensor examples for FRDM-K32L3A6 custom kit with FRDM-STBC-AGM01 in MCUXpresso
- ISSDK enablement for FXPS7250A4 Analog absolute pressure sensor.
 - Added FXPS7250A4 sensor driver
 - Added sensor example for FRDM-KE15Z kit with FRDMSTBA-PA7250 in MCUXpresso
- ISSDK enablement on LPC55S69-EVK
 - Added sensors examples for LPCXpresso55S69 custom kit with FRDM-STBC-AGM01 in MCUXpresso
- ISSDK enablement on MEK-MIMX8QM
 - Enabled on-board sensors (FXOS8700, FXAS21002, MPL3115, ISL29023) examples for MEK-MIMX8QM in MCUXpresso
- Added MCUXpresso IDE support for pedometer examples for kits based on FRDM-STBC-AGM01, FRDM-STBC-AGM04 and FRDM-STBC-MULT2-B, and on-board sensor kits based on FRDM-KL25Z and FRDM-KL27Z

10.3 Delivered in ISSDK v1.6

- ISSDK middleware component integrated with MCU SDK 2.3 Rel7 ecosystem
- ISSDK enablement on EVK-MIMXRT1050
 - Added GPIO abstraction layer

Release notes for ISSDK v1.8

- Added sensors examples for EVK-MIMXRT1050 custom kit with AGM01 in MCUXpresso

- ISSDK enablement on LPC5411x
 - Added GPIO abstraction layer
 - Added custom kit examples for AGM01 and AGMP03 in MCUXpresso
- ISSDK enablement on KE15Z
 - Added kit examples for MPXV5004DP in MCUXpresso
 - Added sensor driver and sample applications for MPXV5004DP
 - FRDM-KE15Z analog example project for MPXV5004DP
- Added orientation demos with Host I/O support (AGM01)
- ISSDK enablement on FRDM-K32W042
 - Added GPIO abstraction layer
 - Added sensors examples for FRDM-K32W042 custom kit with AGM01 in MCUXpresso

10.4 Delivered in ISSDK v1.5

- ISSDK middleware component integrated with MCU SDK 2.2 Rel6 ecosystem.
- ISSDK project generation module updated to support MCUXpresso IDE.
- ISSDK kits sensor and algorithm example projects are now supported with MCUXpresso IDE.
- Added additional sensor examples:
 - FRDM-KL27Z on-board MAG3110 examples
 - FXAS21002 SPI example
- Added STB-CE host protocol compliant demo sources supported with STB-CE (Freedom Sensor ToolBox Community Edition).

10.5 Delivered in ISSDK v1.1

- ISSDK middleware component integrated with MCU SDK 2.1 Rel5 ecosystem.
- Adoption of KSDK 2.0 CMSIS driver implementations.
- Added FRDM-K64F-AGM04 kit.
- Created sensor driver for FXPQ3115 pressure/bio-compatible sensor.
- Added FRDMKL27-B3115 kit.
- Added FRDM-KL25Z as an MMA8451 kit.
- Added FRDM-KL27Z as an MMA8451 kit.
- Added FreeRTOS sensor fusion algorithm examples for FRDM-K64F-AGM04.
- Added bare metal sensor fusion algorithm examples for FRDM-K64F-AGM01 and FRDM-K22F-AGM01.
- Added pedometer algorithm example for FRDM-K64F-AGM04.
- Added pedometer algorithm example for FRDM-KL25Z as an MMA8451 Kit and FRDM-KL27Z as an MMA8451 kit.

10.6 Delivered in ISSDK v1.0

- ISSDK middleware component introduced and integrated with MCU SDK 2.0 ecosystem.
- Designed ISSDK middleware component design into MCU SDK 2.0 ecosystem.
- Created sensor drivers for MMA845X, MMA865X, FXLS8471, MMA8491, FXLC95000, FXAS21002, FXOS8700, MMA9553 and MPL3115 sensors.
- Added FRDM-K64F-AGM01 kit.
- Added FRDM-K64F-MULT2B kit.
- Added FRDM-K22F-AGM01 kit.
- Added FRDM-K22F-SA9500 kit.

- Added FRDMKL25-A8471 kit.
- Added FRDMKL25-A8491 kit.
- Added FRDMKL25-P3115 kit.
- Added FreeRTOS sensor fusion algorithm examples for FRDM-K64F-AGM01, FRDM-K22F-AGM01 and FRDM-K64F-MULT2B kits.
- Added bare metal sensor fusion algorithm examples for FRDM-K64F-MULT2B kit.
- Added pedometer algorithm example for FRDM-K64F-AGM01, FRDM-K22F-AGM01 and FRDM-K64F-MULT2B kits.

11 Revision history

| | ion history | Description |
|-----|---------------------|--|
| Rev | Date | Description |
| 4 | 13 August 2024 | Section 2: Added ", MCX" fourth bullet item. Section 2.1, Table 1, added part numbers FXLS8961AF, FXLS8971CF and NMH1000, added a footnote to ten rows in the column "Sensor part number". Section 3, revised as follows: MCUXpresso IDE: support: revised "v11.7.0" to "v11.10.0". IAR Embeded Workbench for ARM: support: revised "v9.30.x" to "v9.60.1". MDK-ARM Microcontroller: support: revised "v5.37" to "v5.38.0". Makefiles support: revised "10-2021.10" to "13.2.1". Section 5, Table 3, revised as follows: Inserted rows for sensor kits FRDMKE15-NMH1000, LPC55S16-EVK-A8961, and LPC55S16-EVK-A8971 Added a footnote to seven rows in the column "Sensor shield board". Section 5, Table 4. revised as follows: Inserted rows for sensor kits FRDM-K22F with A8961, FRDM-K22F with A8971, FRDMKE15-NMH1000, FRDM-MCXA153 with A8974, FRDM-MCXA156 with A8974, FRDM-MCXN947 with A8974, FRDM-MCXW71 with A8974, K32W148-EVK with A8974, KW45B41Z-EVK with A8974, MIMXRT1060-EVK with A8974 |
| | | Add a footnote to twenty rows in the column "Sensor shield board". <u>Section 10.1</u>, revised the section. <u>Section 11</u> updated to conform with NXP's document content hierarchy. |
| 3 | 23 November 2022 | <u>Section 1</u>, revised "IoT" to "industrial and medical IoT" and "relies on the SDK" to "relies on the MCUXpresso SDK" <u>Section 3</u>, revised "v.11.6.0" to "11.7.0" and revised "v9.20.4" to "9.30.x". <u>Section 5</u>, <u>Table 4</u>, added three rows for LPCXpresso55S16 for FRDM-STBA-A8964, -A8967, and -A8974. <u>Section 10.1</u>, revised "2.12.0" to "2.13.0" and added new bullet for "ISSDK FXLS8964AF, FXLS8967AF, FXLS8974CF sensors enablement on LPCXpresso55S16". |
| 2 | 31 May 2022 | Section 2 "Features", added new bulleted list of features and moved sections 2.1 through 2.6 to Section 10. Section 2.1 "Supported sensors", Table 1, revised as follows: Title: Revised "Sensors supported by ISSDK v1.7" to "Sensors supported by ISSDK v1.8". Revised "FXLS896xAFR1" to "FXLS8962AFR1". Revised "FXLS8964AF" to "FXLS8964AFR3" and revised the description of the sensor type. Inserted new table rows for "FXLS8967AFR3" and "FXLS8974CFR3". Section 2.2, revised section title from "Algorithm support" to Supported algorithms". Section 3 "Development tools", revised as follows: Revised "IAR Embedded Workbench for ARM version v9.20.1" to "IAR Embedded Workbench for ARM version v9.20.4". Revised "MDK-ARM Microcontroller Development Kit (Keil) v5.36" to "MDK-ARM Microcontroller Development Kit (Keil) v5.37". Revised "Makefiles support with GCC revision 10-2021.07 from ARM Embedded" to "Makefiles support with GCC revision 10-2021.10 from ARM Embedded". Section 4 "PC configurations", Table 2, removed "Windows 7 /" from the "Operating system" row. Section 5 "Supported development systems", revised as follows: Table 3, added table entry for "FRDM-K22F-A8974". |

Release notes for ISSDK v1.8

Revision history...continued Rev Date Description - Table 4, revised the table title from "Custom sensor kits supported by ISSDK v1.7" to "Custom sensor kits supported by ISSDK v1.8". - Table 4, added table entries for "FRDM-K22F with A8967" and "EVK-MIMXRT1040 with A8974". Section 6 "Release contents", Table 5, revised as follows: - Replaced the "Status" column with "Details" column and added new content in the "Details" column for each row. - Removed the "ISSDK specific drivers" and "Host protocal compliant demo sources" rows from the table. • Section 9 "Known issues", revised "SDK 2.11.0 Rel 15" to "SDK 2.12.0". • Section 10 "Change log", revised as follows: - Inserted new section titled "Change log". - Relocated sections Section 10.1 through Section 10.6 from Section 2 to Section 10. - Section 10.1 "What is new in ISSDK v1.8", revised and added additional content. 1 30 November Initial release for RN00010. This document supercedes ISDK17RN 2021

Legal information

Definitions

Draft — A draft status on a document indicates that the content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included in a draft version of a document and shall have no liability for the consequences of use of such information.

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors and its suppliers accept no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using NXP Semiconductors products, and NXP Semiconductors accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the NXP Semiconductors product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

NXP Semiconductors does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using NXP Semiconductors products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). NXP does not accept any liability in this respect.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

Suitability for use in non-automotive qualified products — Unless this document expressly states that this specific NXP Semiconductors product is automotive qualified, the product is not suitable for automotive use. It is neither qualified nor tested in accordance with automotive testing or application requirements. NXP Semiconductors accepts no liability for inclusion and/or use of non-automotive qualified products in automotive equipment or applications.

In the event that customer uses the product for design-in and use in automotive applications to automotive specifications and standards, customer (a) shall use the product without NXP Semiconductors' warranty of the product for such automotive applications, use and specifications, and (b) whenever customer uses the product for automotive applications beyond NXP Semiconductors' specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies NXP Semiconductors for any liability, damages or failed product claims resulting from customer design and use of the product for automotive applications beyond NXP Semiconductors' standard warranty and NXP Semiconductors' product specifications.

HTML publications — An HTML version, if available, of this document is provided as a courtesy. Definitive information is contained in the applicable document in PDF format. If there is a discrepancy between the HTML document and the PDF document, the PDF document has priority.

Translations — A non-English (translated) version of a document, including the legal information in that document, is for reference only. The English version shall prevail in case of any discrepancy between the translated and English versions.

Security — Customer understands that all NXP products may be subject to unidentified vulnerabilities or may support established security standards or specifications with known limitations. Customer is responsible for the design and operation of its applications and products throughout their lifecycles to reduce the effect of these vulnerabilities on customer's applications and products. Customer's responsibility also extends to other open and/or proprietary technologies supported by NXP products for use in customer's applications. NXP accepts no liability for any vulnerability. Customer should regularly check security updates from NXP and follow up appropriately. Customer shall select products with security features that best meet rules, regulations, and standards of the intended application and make the ultimate design decisions regarding its products and is solely responsible for compliance with all legal, regulatory, and security related requirements concerning its products, regardless of any information or support that may be provided by NXP.

NXP has a Product Security Incident Response Team (PSIRT) (reachable at <u>PSIRT@nxp.com</u>) that manages the investigation, reporting, and solution release to security vulnerabilities of NXP products.

 $\ensuremath{\mathsf{NXP}}\xspace{\mathsf{B.V.}}$ — NXP B.V. is not an operating company and it does not distribute or sell products.

Trademarks

Notice: All referenced brands, product names, service names, and trademarks are the property of their respective owners.

NXP — wordmark and logo are trademarks of NXP B.V.

AMBA, Arm, Arm7, Arm7TDMI, Arm9, Arm11, Artisan, big.LITTLE, Cordio, CoreLink, CoreSight, Cortex, DesignStart, DynamIQ, Jazelle, Keil, Mali, Mbed, Mbed Enabled, NEON, POP, RealView, SecurCore, Socrates, Thumb, TrustZone, ULINK, ULINK2, ULINK-ME, ULINK-PLUS, ULINKpro, µVision, Versatile — are trademarks and/or registered trademarks of Arm Limited (or its subsidiaries or affiliates) in the US and/or elsewhere. The related technology may be protected by any or all of patents, copyrights, designs and trade secrets. All rights reserved.

Release notes for ISSDK v1.8

Tables

| Tab. 1. | Sensors supported by ISSDK v1.8 | 2 |
|---------|---|---|
| Tab. 2. | PC configurations | 4 |
| | Standard sensor kits supported by ISSDK | |
| | v1.8 | 4 |

| Tab. 4. | Custom sensor kits supported by ISSDK | |
|---------|---------------------------------------|---|
| | v1.85 | 5 |
| Tab. 5. | Release contents6 | 3 |
| Tab. 6. | MISRA exception rules7 | 7 |

Release notes for ISSDK v1.8

Contents

| 1 | Overview | 2 |
|------|-------------------------------|----|
| 2 | Features | 2 |
| 2.1 | Supported sensors | 2 |
| 2.2 | Supported algorithms | 3 |
| 3 | Development tools | 4 |
| 4 | PC configurations | 4 |
| 5 | Supported development systems | 4 |
| 6 | Release contents | |
| 7 | MISRA compliance | 7 |
| 8 | Open and closed defects | 8 |
| 8.1 | ISSDK v1.8 open defects | |
| 8.2 | ISSDK v1.8 closed defects | 8 |
| 9 | Known issues | 8 |
| 10 | Change log | 9 |
| 10.1 | What is new in ISSDK v1.8 | 9 |
| 10.2 | What is new in ISSDK v1.7 | 9 |
| 10.3 | Delivered in ISSDK v1.6 | 10 |
| 10.4 | Delivered in ISSDK v1.5 | 11 |
| 10.5 | Delivered in ISSDK v1.1 | 11 |
| 10.6 | Delivered in ISSDK v1.0 | 11 |
| 11 | Revision history | 13 |
| | Legal information | 15 |

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.

© 2024 NXP B.V.

All rights reserved.

For more information, please visit: https://www.nxp.com

Document feedback Date of release: 15 August 2024 Document identifier: RN00010